

Customer No.: 31561
Application No.: 10/710,697
Docket NO.: 12866-US-PA

AMENDMENT

In the Claims:

Claim 1. (original) A circuit connecting structure, for a circuit carrier, wherein the circuit carrier comprises a first patterned circuit layer and a second patterned circuit layer, the circuit connecting structure comprising:

a first insulating layer, wherein a first via hole is formed therefrom;

a second insulating layer, wherein a second via hole is formed therefrom, and the second insulating layer is formed over the first insulating layer;

a conductive pad, disposed between the first insulating layer and the second insulating layer, wherein two surfaces of the conductive pad are respectively connected to the first via hole and the second via hole;

a first conductive layer, disposed over the first insulating layer away from a surface of the second insulating layer and in the first via hole for coupling to the conductive pad, and the first conductive layer serving to form the first patterned circuit layer; and

a second conductive layer, disposed over the second insulating layer away from a surface of the first insulating layer and in the second via hole for coupling to the conductive pad, and the second conductive layer serving to form the second patterned circuit layer.

Claim 2. (original) The structure as recited in claim 1, wherein the conductive pad comprises copper.

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Claim 3. (original) The structure as recited in claim 1, wherein the first conductive layer comprises copper.

Claim 4. (original) The structure as recited in claim 1, wherein the second conductive layer comprises copper.

Claim 5. (original) The structure as recited in claim 1, wherein the first insulating layer comprises epoxy resin.

Claim 6. (original) The structure as recited in claim 1, wherein the second insulating layer comprises epoxy resin.

Claim 7. (cancelled).